| | connector CES | S |
|-------------------------------|--|------------------------------|
| | SPECIFICATION | I |
| 宏致 | x 電子股份有阻 | 灵公司 |
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| | Taoyuan County 320, Taiwan (R.O | .C.) |
| | TEL: +886-3-463-2808 FAX: +886-3-463-1800 | |
| SPEC. NO.: PS-51 | 646-XXXX-XXX REVI | SION: O |
| PRODUCT NAME: | 0.8 mm PITCH ZIF FPC CONN. | SMT R/A T/C TYPE |
| PRODUCT NO: | 51646 SERIES | |
| PREPARED | CHECKED: | APPROVED: |
| LI JIN DATE: 2015/03/17 | BRAVE DATE: 2015/03/17 | FRANK DATE: 2015/03/17 |
| | | |

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| | es la | Aces P/I | N: 51646 Series | | | | | | | |
|--------------------------------------|--|---|---------------------|----------------------------|--|--|--|--|--|--|
| TITLE: | TITLE: 0.8 mm PITCH FPC CONNECTOR SMT R/A T/C TYPE | | | | | | | | | |
| RELEASE | DATE: 2015/03/17 | REVISION: 0 | ECN No: ECN-1503228 | PAGE: 2 OF 9 | | | | | | |
| 1 2 3 4 5 6 7 8 | SCOPE APPLICABLE DO REQUIREMENTS PERFORMANCE INFRARED REFL PRODUCT QUAL | OCUMENTS S LOW CONDITION LIFICATION AND TE | ST SEQUENCE | 4 4 4 5 7 8 | | | | | | |

| ACES | Aces P/N: 51646 Series |
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| TITLE: 0.8 mm PITCH FPC CONNE | CTOR SMT R/A T/C TYPE |

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REVISION: 0

1 Revision History

RELEASE DATE: 2015/03/17

| Rev. | ECN # | Revision Description | Prepared | Date |
|------|-------------|--|----------|------------|
| 1 | ECN-1409137 | NEW SPEC | LÍ JIN | 2014/09/10 |
| 2 | ECN-1410399 | Modify the Actuator output pull (1.0->0.5) | LI JIN | 2015/01/05 |
| 0 | ECN-1503228 | 結案發行 | LI JIN | 2015/03/17 |
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| | Aces P/N: 51646 Series |
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| Т | ITLE: 0.8 mm PITCH FPC CONNECTOR SMT R/A T/C TYPE |
| REL | EASE DATE: 2015/03/17 REVISION: O ECN No: ECN-1503228 PAGE: 4 OF 9 |
| 2 | SCOPE |
| | This specification covers performance, tests and quality requirements for 0.8 mm pitch FPC Connector SMT R/A TYPE. |
| 3 | APPLICABLE DOCUMENTS |
| | EIA-364: ELECTRONICS INDUSTRIES ASSOCIATION |
| 4 | REQUIREMENTS |
| | 4.1 Design and Construction |
| | 4.1.1 Product shall be of design, construction and physical dimensions specified |
| | on applicable product drawing. |
| | 4.1.2 All materials conform to R.o.H.S. and the standard depends on TQ-WI-140101. |
| | 4.2 Materials and Finish |
| | 4.2.1 Contact: High performance copper alloy (Phosphor Bronze) Finish: (a) Contact Area: Refer to the drawing. (b) Under plate: Refer to the drawing. |
| | (c) Solder area: Refer to the drawing. 4.2.2 Housing: Thermoplastic or Thermoplastic High Temp., UL94V-0 4.2.3 Actuator: Thermoplastic or Thermoplastic High Temp., UL94V-0 4.2.4 Fitting Nail: Copper Alloy, Finish: Refer to the drawing. |
| | 4.3 Ratings |
| | 4.3.1 Voltage: 50 Volts AC(per pin) 4.3.2 Working voltage less than 36 volts (per pin) 4.3.3 Current: 0.5 Amperes (per pin) 4.3.4 Operating Temperature : -25°C to +85°C |
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| | |
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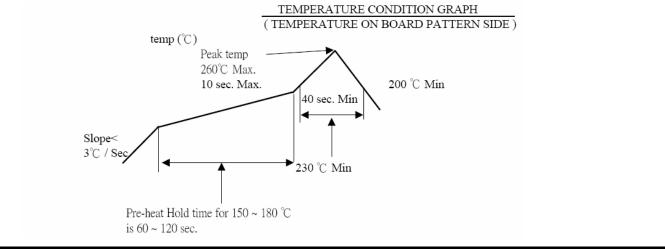
| | Aces P/N: 51646 Se | ries | | |
|---|---|--|--------------|--|
| E: 0.8 mm PITCH FPC CO | NNECTOR SMT R/A T/C T | YPE | | |
| E DATE: 2015/03/17 REVISION | N: O ECN No: EC | CN-1503228 | PAGE: 5 OF S | |
| erformance 1. Test Requirements and P | rocedures Summary | | | |
| ltem | Requirement | Stand | dard | |
| Examination of Product | Product shall meet requirements of applicable product drawing and specification. | Visual, dimensional and | | |
| | ELECTRICAL | • | | |
| Low Level Contact Resistance | 20 m Ω Max. (initial) per contact ΔR 10 m Ω Max. | Mate connectors, circuit, 20mV Max Max. (EIA-364-23) | | |
| Insulation Resistance | 500 M Ω Min. | Unmated connectors, apply 500 V DC between adjacent terminals. (EIA-364-21) | | |
| Dielectric Withstanding Voltage | No discharge, flashover or breakdown. Current leakage: 1 mA max. | 300 VAC Min.at sea level for 1 minute.Test between adjacent contacts of unmated connectors. (EIA-364-20) | | |
| Temperature rise | 30℃ Max. Change allowed | Mate connector: measure the temperature rise at rated current until temperature stable. The ambient condition is still air at 25°C (EIA-364-70, METHOD1,CONDITION1) | | |
| | MECHANICAL | | | |
| Item | Requirement | | Indard | |
| Durability | 30 cycles. | The sample should be mount the tester and fully mated an unmated the number of cycle specified at the rate of 25.4 ± 3mm/min. (EIA-364-09) | | |
| Actuator Insertion / Withdrawing Force | Refer to page.9 Actuator insertion/withdrawing force | A connector shall be soldered or | | |
| Terminal / Housing Retention Force | 0.15kgf MIN. | | | |

| | Aces P/N: | 51646 Seri | ies | | |
|--|--|--|---|------------------|--|
| E: 0.8 mm PITCH F | PC CONNECTOR SM | T R/A T/C TY | ΈE | | |
| E DATE: 2015/03/17 | REVISION: 0 | ECN No: ECN | N-1503228 | PAGE: 6 OF 9 | |
| Fitting Nail /Housing Retention Force | 0.15kgf MIN. | | Apply axial pull out force at the speed rate of 25.4 ± 3 mm/minute. On the fitting nail assembled in the housing. The electrical load condition shall be 100 mA maximum for all contacts. Subject to a simple harmonic motion having amplitude of 0.76mm (1.52mm maximum total excursion) in frequency between the limits of 10 and 55 Hz. The entire frequency range, from 10 to 55 Hz and return to 10 Hz, shall be traversed in approximately 1 minute. This motion shall be applied for 2 hours in each of three mutually perpendicular directions. (EIA-364-28 Condition I) Subject mated connectors to 50 G's (peak value) half-sine shock pulses of 11 milliseconds duration. Three shocks in each direction shall be applied along the three mutually perpendicular axes of the test specimen (18 shocks). The electrical load condition shall be DC 100mA maximum for all contacts. (EIA-364-27, test condition A) | | |
| Vibration | 1 μ s Max. | | | | |
| Shock (Mechanical) | 1 μ s Max. | | | | |
| | ENVIRON | | | | |
| Item | Require | | Sta | ndard | |
| Hand Soldering Temp Resistance | erature Appearance: No Test Sequence (Lead Free) | | ≧ 350 °C,3 | Bsec at least. | |
| Resistance to Reflow Soldering Heat | Second Reflow p be taken after the temperature has | e product down to room alification and Group 9(Lead | | lin., 40sec Min. | |

| | | Aces P/N: 5 | 1646 Ser | ies | | |
|---------------------------------|--|---|-------------------|---|--|--|
| TITLE: 0.8 mm PITCH F | PC CONNE | CTOR SMT | R/A T/C T | (PE | | |
| LEASE DATE: 2015/03/17 | REVISION: 0 | | ECN No: EC | N-1503228 | PAGE: 7 OF 9 | |
| Thermal Shock | | Product Quali t Sequence Gro | | Mate module as follow condition $-55 \pm 0/-3$ °C, 30 $\pm 85 \pm 3/-0$ °C, 3 (EIA-364-32, te | o for 5 cycles.) minutes 0 minutes | |
| Humidity | | See Product Qualification and Test Sequence Group 3 | | Mated Connector 40°C,90~95% RH, 96 hours (EIA-364-31,condition A, Method | | |
| Temperature life | | Product Quali t Sequence Gro | | Subject mated temperature life hours. (EIA-364-17, Te | e at 85℃ for 96 | |
| Salt Spray For Gold Plating) | | Product Quali t Sequence Gro | | Subject mated/ connectors to 5 concentration, 3 (I) Gold flash fo (II) Gold plating hours. (EIA-364-26) | unmated % salt-solution 35℃ r 8 hours | |
| Solder ability | Solo mini cove Golo Solo mini | plating: der able area sh imum of 95% sc erage. d plating: der able area sh imum of 75% sc erage | older all have | Subject the test into the flux for then into solder Temperature at 4~5 sec. (EIA-364-52) | bath, | |

Note 1. Flowing Mixed Gas shell be conduct by customer request.

6 INFRARED REFLOW CONDITION



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| CES | Ac | es P/N | N: 51 | 646 | Seri | es | | | | |
|---|---|--------|--------------|-------|--------|-------|-------|---|-----|-----------------|
| ITLE: 0.8 mm PITCH FPC CONNE | ЕСТО | OR S | MTR | /A T/ | С ТҮІ | PE | | | | |
| EASE DATE: 2015/03/17 REVISION: O | | | | ECN N | b: ECN | -1503 | 3228 | | PA | .ge: 8 o |
| PRODUCT QUALIFICATION | PRODUCT QUALIFICATION AND TEST SEQUENCE | | | | | | | | | |
| Test Group | | | | | | | | | | |
| Test or Examination | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 |
| | | | | Т | est Se | quen | се | | | |
| Examination of Product | | | 1、7 | 1、6 | 1、4 | | 1、6 | | 1、3 | 1 |
| Low Level Contact Resistance | | 1、4 | 2、10 | 2、9 | 2、5 | | 2 • 7 | | 4 | |
| Insulation Resistance | | | 3、9 | 3、8 | | | | | | |
| Dielectric Withstanding Voltage | | | 4 • 8 | 4 \ 7 | | | | | | |
| Temperature Rise | 1 | | | | | | | | | |
| Durability | | | | | | | 4 | | | |
| Vibration | | 2 | | | | | | | | |
| Shock (Mechanical) | | 3 | | | | | | | | |
| Thermal Shock | | | 5 | | | | | | | |
| Humidity | | | 6 | | | | | | | |
| Temperature Life | | | | 5 | | | | | | |
| Salt Spray(Only For Gold Plating) | | | | | 3 | | | | | |
| Solder ability | | | | | | 1 | | | | |
| Actuator Insertion / Withdrawing Force | | | | | | | 3、5 | | | |
| Terminal / Housing Retention Force | | | | | | | | 1 | | |
| Fitting Nail /Housing Retention Force | | | | | | | | 2 | | |
| Resistance to Reflow Soldering Heat | | | | | | | | | 2 | |
| Hand Soldering Temperature Resistance | | | | | | | | | | 2 |
| Sample Size | 2 | 4 | 4 | 4 | 4 | 2 | 4 | 4 | 4 | 4 |

| _ | | | | | | | | |
|----------|------------------------|--------------------------|---------------------------|---------------------|--------------|--|--|--|
| | Aces P/N: 51646 Series | | | | | | | |
| TITLE: | 0.8 mm | PITCH FPC CON | NECTOR SMT | R/A T/C TYPE | | | | |
| ELEASE [| DATE: 2015/03 | /17 REVISION | : 0 | ECN No: ECN-1503228 | PAGE: 9 OF 9 | | | |
| B AC | TUATOF | R INSERTION/V | | | | | | |
| | | | UNIT: Kgf | | | | | |
| | NO. OF Ckt. | Insertion Force (Max) | Withdrawal Force (Min) | | | | | |
| | 30 | 1.6 | 0.5 | | | | | |
| | | | | u | | | | |
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